

# METHODS AND APPARATUS FOR CONTROLLING ELECTROLYTE FLOW FOR UNIFORM PLATING

## ABSTRACT OF THE DISCLOSURE

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10 The present invention provides apparatus and methods for controlling flow dynamics of a plating fluid during a plating process. The invention achieves this fluid control through use of a diffuser membrane. Plating fluid is pumped through the membrane; the design and characteristics of the membrane provide a uniform flow pattern to the plating fluid exiting the membrane. Thus a work piece, upon which a metal or other conductive material is to be deposited, is exposed to a uniform flow of plating fluid.